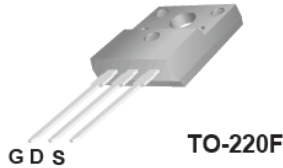


TSF60R190S1

600V 20A N-Channel SJ-MOSFET

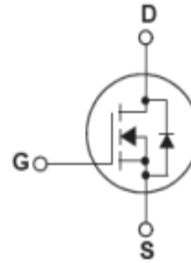
General Description

Truesemi SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance. This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.



Features

- 650V @T_J = 150 °C
- Typ. RDS(on) = 0.19Ω
- Ultra Low gate charge (typ. Q_g = 70nC)
- 100% avalanche tested



Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source Voltage	600	V
I _D	Drain Current -Continuous (TC = 25°C) -Continuous (TC = 100°C)	20* 12.6*	A
I _{DM}	Drain Current – Pulsed (Note 1)	62*	A
V _{GSS}	Gate-Source voltage	±30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	485	mJ
I _{AR}	Avalanche Current (Note 1)	3.5	A
E _{AR}	Repetitive Avalanche Energy (Note 1)	1	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	15	V/ns
P _D	Power Dissipation (TC = 25°C) -Derate above 25°C	35 0.3	W W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	°C

* Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	Value	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	3.7	°C/W
R _{θCS}	Thermal Resistance, Case-to-Sink Typ.	--	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	80	°C/W

Electrical Characteristics TC = 25°C unless otherwise noted

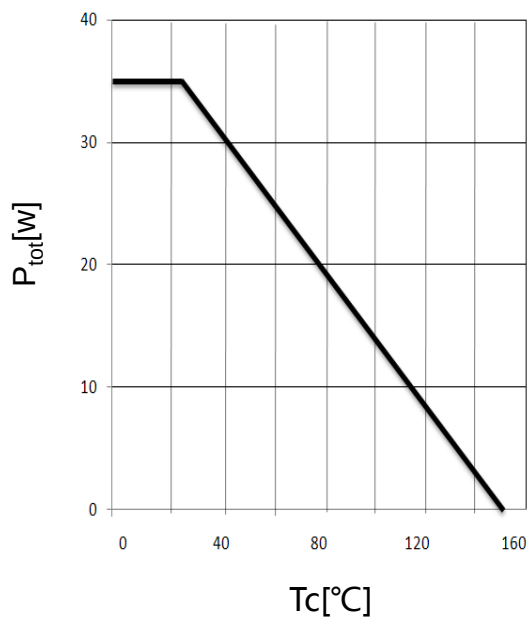
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA, T _J = 25℃	600	--	--	V
		V _{GS} = 0V, I _D = 250μA, T _J = 150℃	--	650	--	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25℃	--	0.6	--	V/℃
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 600V, V _{GS} = 0V -T _J = 150℃	--	-- 10	1 --	μA μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V	--	--	-100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.0	--	4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 10A	--	0.16	0.19	Ω
g _{FS}	Forward Trans conductance	V _{DS} = 20V, I _D = 20A (Note 4)	--	16	--	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	--	1440	--	pF
C _{oss}	Output Capacitance		--	370	--	pF
C _{rss}	Reverse Transfer Capacitance		--	11	--	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 400V, I _D = 10A R _G = 20Ω(Note 4, 5)	--	15	--	ns
t _r	Turn-On Rise Time		--	11	--	ns
t _{d(off)}	Turn-Off Delay Time		--	110	--	ns
t _f	Turn-Off Fall Time		--	9	--	ns
Q _g	Total Gate Charge	V _{DS} = 480V, I _D = 10A V _{GS} = 10V (Note 4, 5)	--	70	90	nC
Q _{gs}	Gate-Source Charge		--	7.8	--	nC
Q _{gd}	Gate-Drain Charge		--	9	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	20	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	60	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _F = 10A	--	1	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _F = 10A di _F /dt =100A/μs (Note 4)	--	475	--	ns
Q _{rr}	Reverse Recovery Charge		--	5.8	--	μC
I _{rrm}	Peak reverse recovery Current				35	--

NOTES:

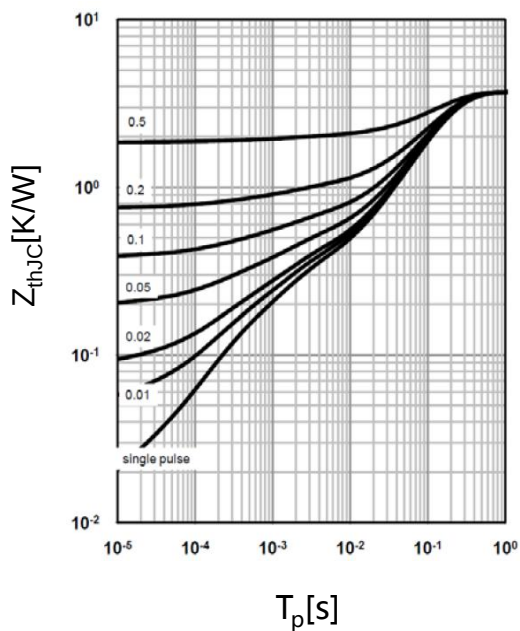
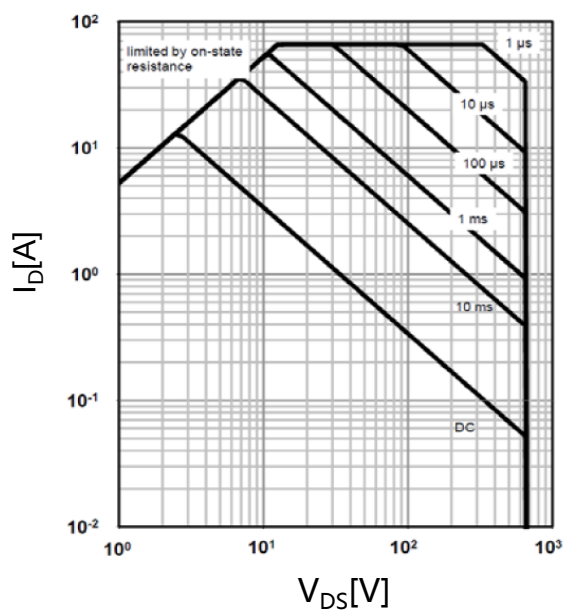
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_{AS}=3.5A, V_{DD}=50V$, Starting $T_J=25^\circ C$
3. $I_{SD}\leq 20A, di/dt \leq 200A/\mu s, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ C$
4. Pulse Test: Pulse width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

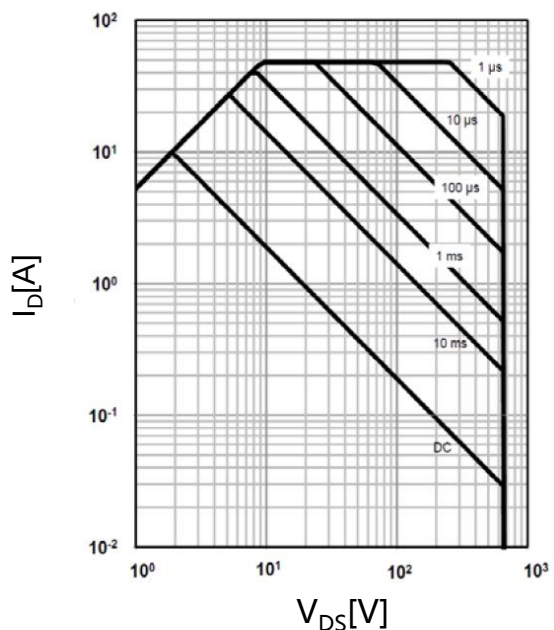
Power dissipation



Max. transient thermal impedance

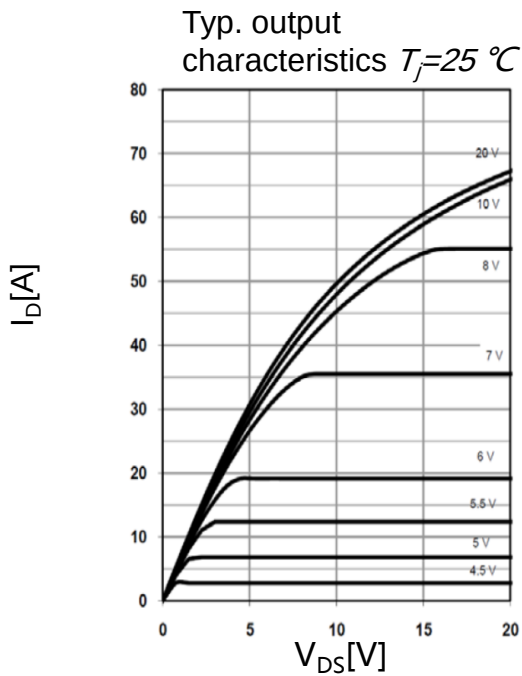
Safe operating area $T_c=25\text{ }^{\circ}\text{C}$ 

$I_D=f(V_{DS}); T_c=25\text{ }^{\circ}\text{C}; V_{GS} > 7\text{V};$
 $D=0; \text{parameter } t_p$

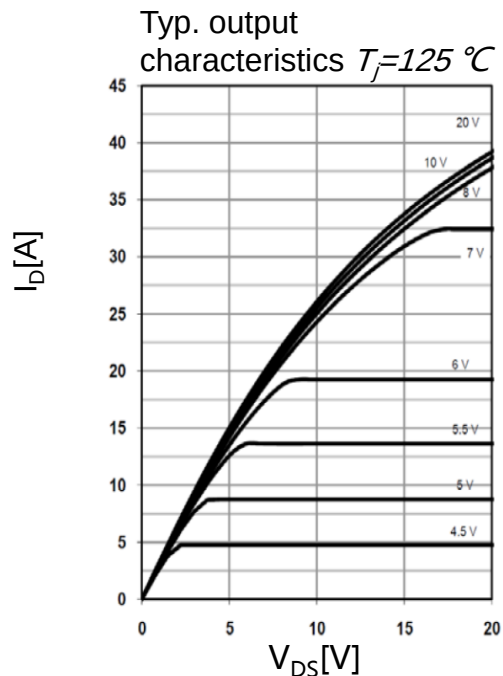
Safe operating area $T_c=80\text{ }^{\circ}\text{C}$ 

$I_D=f(V_{DS}); T_c=80\text{ }^{\circ}\text{C}; V_{GS} > 7\text{V};$
 $D=0; \text{parameter } t_p$

Typical Performance Characteristics

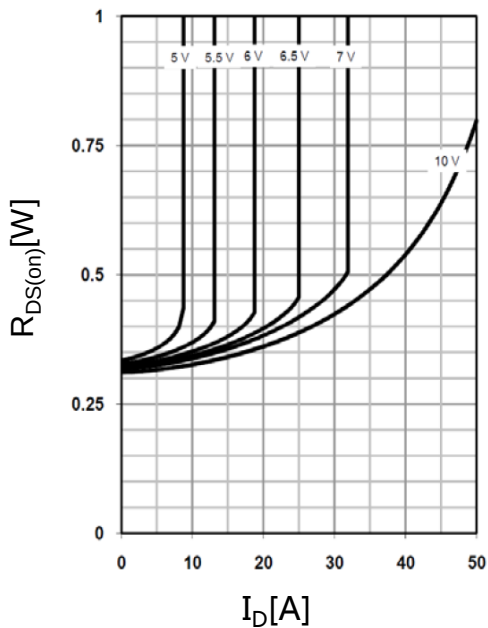


$I_D=f(V_{DS}); T_j=25^\circ\text{C}$; parameter: V_{GS}



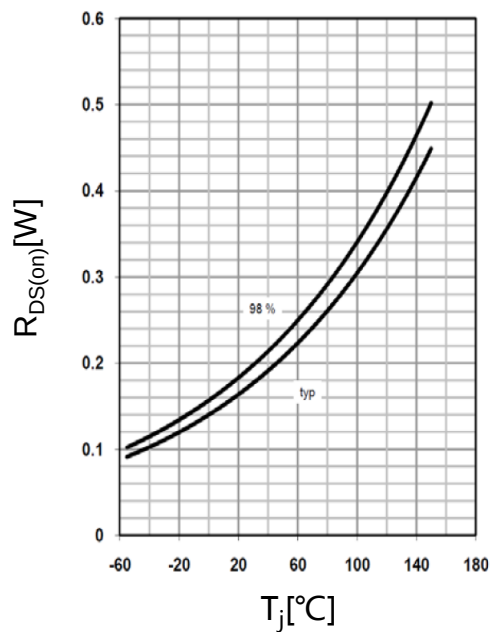
$I_D=f(V_{DS}); T_j=125^\circ\text{C}$; parameter: V_{GS}

Typ. drain-source on-state resistance



$R_{DS(on)}=f(I_D); T_j=125^\circ\text{C}$;
parameter: V_{GS}

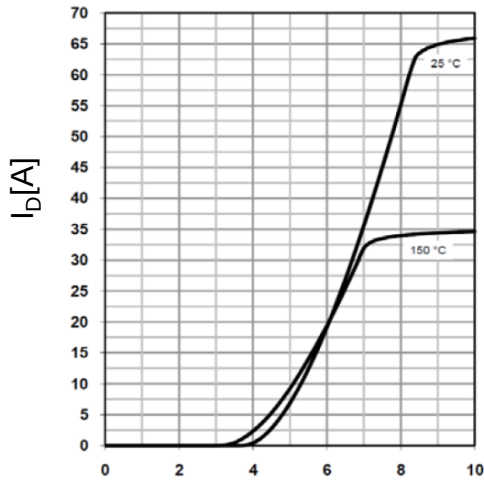
Typ. drain-source on-state resistance



$R_{DS(on)}=f(T_j); I_D=7.3\text{ A}; V_{GS}=10\text{ V}$

Typical Performance Characteristics

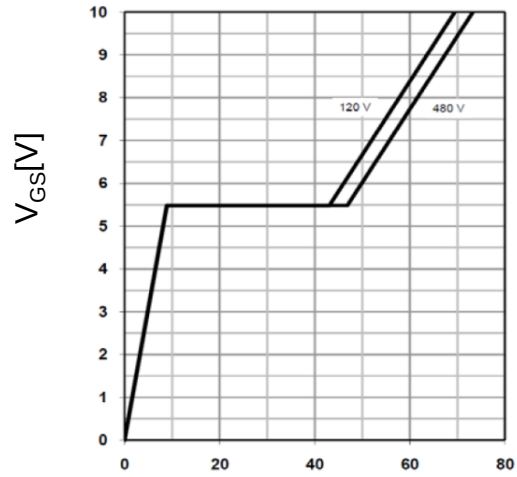
Typ. transfer characteristics



$V_{GS}[V]$

$I_D=f(V_{GS}); V_{DS}=20V$

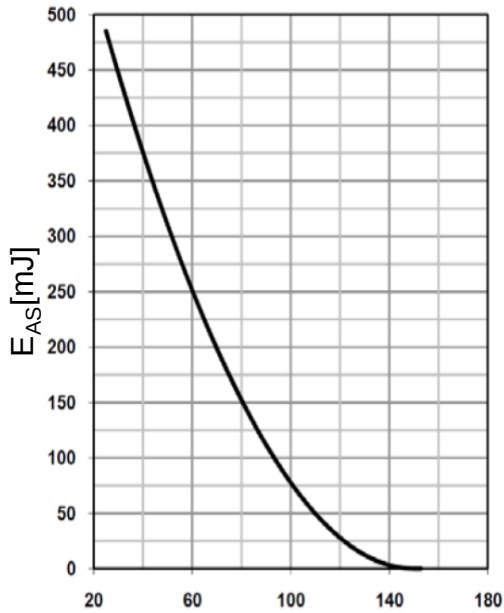
Typ. gate charge



$QV_G[nC]$

$V_{GS}=f(Q_g), I_D=11 A$ pulsed

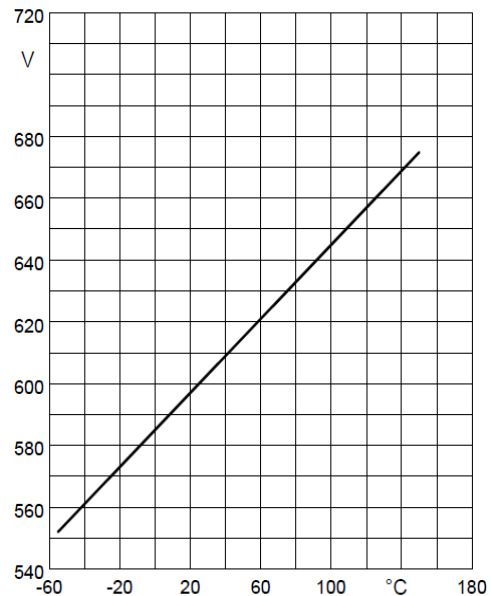
Avalanche energy



$T_j[^\circ C]$

$E_{AS}=f(T_j); I_D=3.5 A; V_{DD}=50 V$

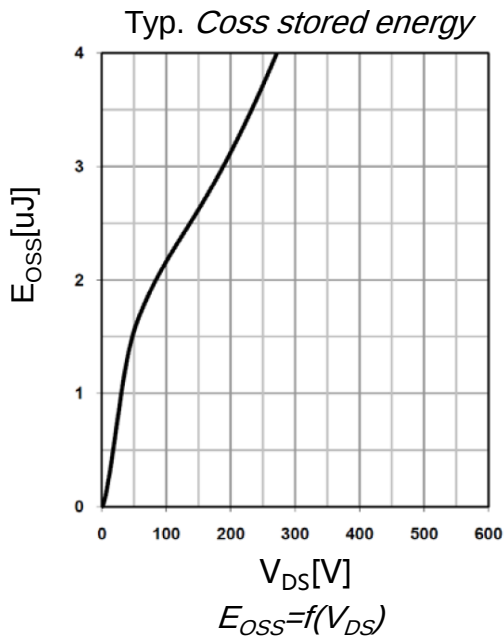
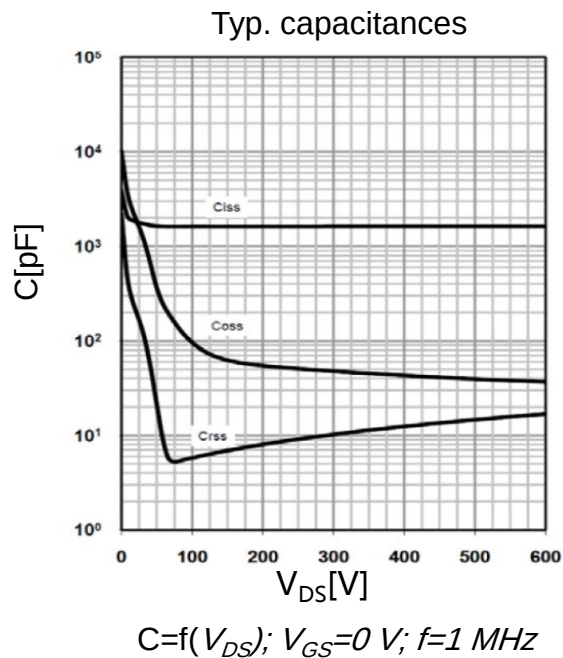
Drain-source breakdown voltage



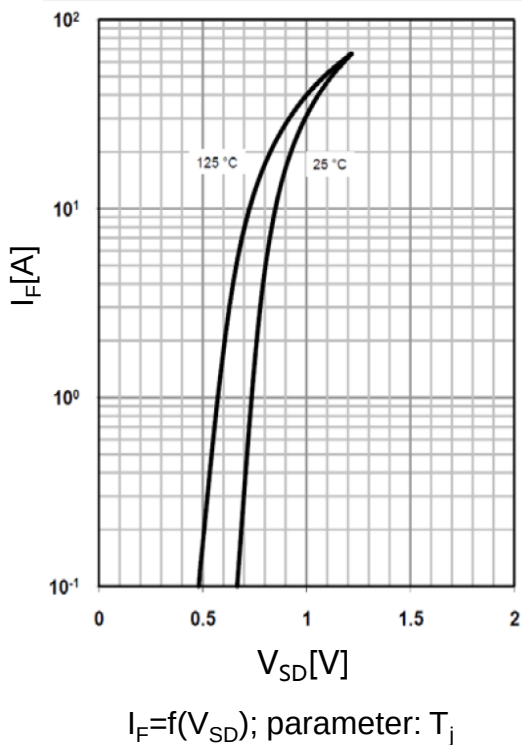
$T_j[^\circ C]$

$V_{BR(DSS)}=f(T_j); I_D=1.0 mA$

Typical Performance Characteristics

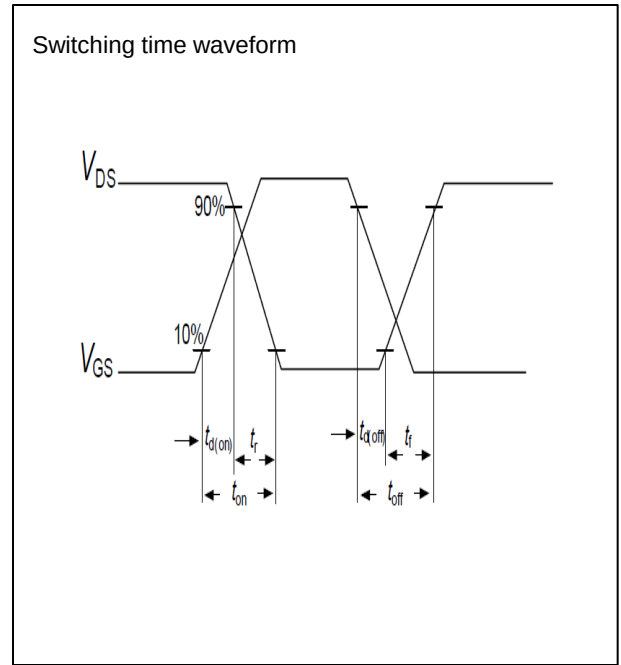
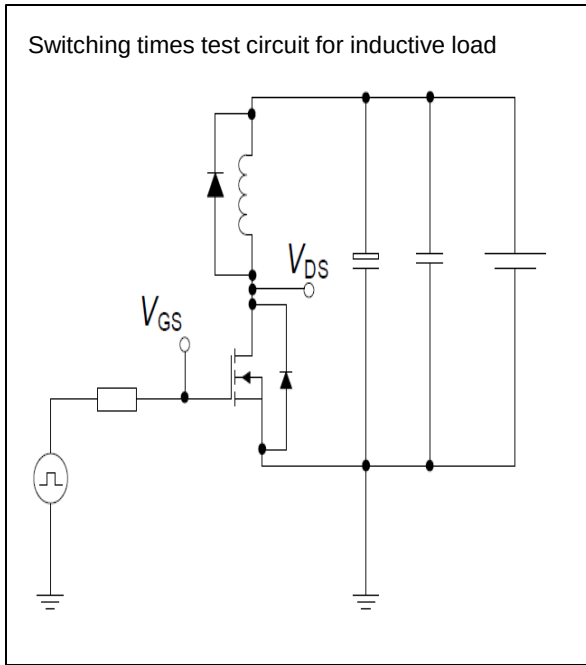


Forward characteristics of reverse diode

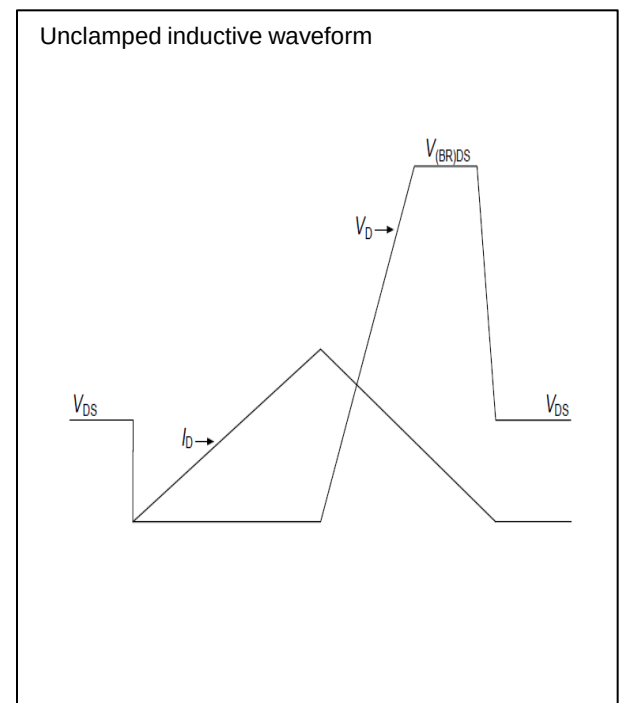
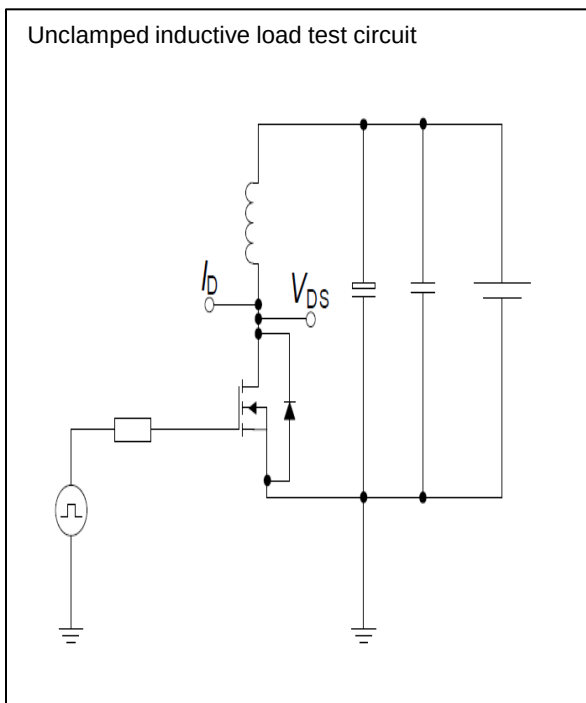


Test circuits

Switching times test circuit and waveform for inductive load

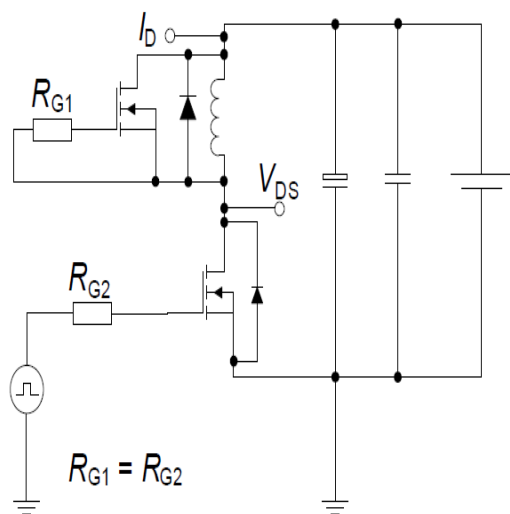


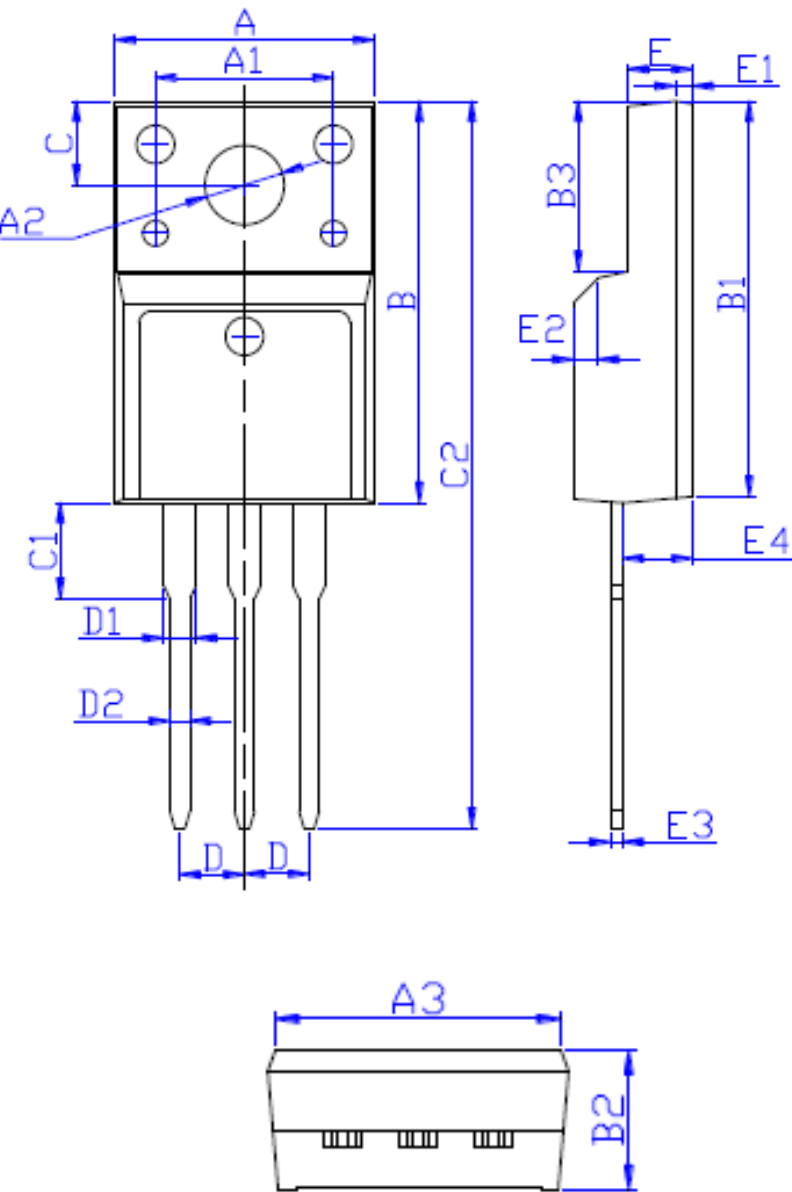
Unclamped inductive load test circuit and waveform



TSF60R190S1 600V 20A N-Channel SJ-MOSFET

Test circuit for diode characteristics





DIM	MILLIMETERS
A	10.16±0.30
A1	7.00±0.20
A2	3.12±0.20
A3	9.70±0.30
B	15.90±0.50
B1	15.60±0.50
B2	4.70±0.30
B3	6.70±0.30
C	3.30±0.25
C1	3.25±0.30
C2	28.70±0.50
D	Typical 2.54
D1	1.47 (MAX)
D2	0.80±0.20
E	2.55±0.25
E1	0.70±0.25
E2	1.0×45°
E3	0.50±0.20
E4	2.75±0.30